ABSTRACT

A NOVEL LINEAR CMP TOOL DESIGN WITH CLOSED LOOP SLURRY DISTRIBUTION

An apparatus for closed loop slurry distribution during semiconductor wafer polishing operations. The traditional peristaltic pump for slurry supply is eliminated thus eliminating irregularities in the conventional slurry supply. Common platform mounting of the slurry reservoir and the polishing apparatus resulting in concurrent and identical motion of the slurry supply reservoir and the polishing apparatus. The polishing medium is mounted on the outside of a cylinder as opposed to the conventional table mounting, the polishing medium rotates around the axis of the cylinder on which this polishing medium is mounted. The polishing pads are in direct physical contact with the slurry supply without the intervention of any slurry pumping arrangement.

(FIGURE 3 IS SUGGESTED FOR PUBLICATION)